

Notification on the Update of Country of Origin Label Information

Dear Customers,

Recently, China Customs has continuously tightened the supervision over the declaration of origin for integrated circuits (HS Code: 8542), and has designated origin inspection and assessment as key supervision procedures. To ensure the compliance and smoothness of import and export operations in our cooperation, and to prevent risks such as customs clearance delays caused by "discrepancies between documents" and "discrepancies between documents and goods" in origin information, in accordance with relevant laws and regulations including the Customs Law of the People's Republic of China and the Regulations of the People's Republic of China on the Origin of Import and Export Goods, our company hereby notifies you of the update to the origin label information for integrated circuit products as follows:

Background and Core Requirements of Customs Supervision

At present, the division of labor in the global integrated circuit industry chain is becoming increasingly refined, and there are variations in non-preferential origin rules across different countries. China Customs adopts the **wafer manufacturing location (wafer fabrication site)** where substantial transformation is completed as the core criterion for determining origin. The traditional practice of marking general origin information such as "COO", "Origin" and "Made in" can no longer meet the supervision requirements of Customs.

Customs clearly stipulates that the determination of origin shall be mainly based on the wafer production information (including but not limited to COD, CCO, Diffusion/Diffused in, FAB, etc.) stated in the original manufacturer's packing list, original manufacturer's invoice and product labels. This ensures that the origin information accurately corresponds to the actual production processes.

Updated Content of Label Information

Starting from January 2026, the label information of all import and export products supplied by our company to your company will be uniformly updated as follows:

- The marking of "COO (Country of Origin)" will be canceled, and general expressions of origin will no longer be used;

- "COD (Country of Diffusion/FAB)" will be added, which shall be filled with the wafer manufacturing location (wafer fabrication site) and must be consistent with the original manufacturer's wafer manufacturing information;
- "COA (Country of Assembly)" will be added, which shall be filled with the packaging and assembly location, so as to clearly distinguish between the wafer manufacturing location and the packaging/assembly location.

Supplementary Provisions

For matters not covered in this notification, we will conduct friendly negotiations with your company in accordance with the relevant laws and regulations of China's customs and tax authorities. We would like to express our gratitude for your understanding and support. We will continue to provide compliant and efficient services to ensure win-win cooperation between both parties.

MEMSIC

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